

Product Change Notification

(Notification - P1608043-DIGI)

August 19, 2016

To: Our Valued Digi-Key, Inc. Customer

Overview: The purpose of this notification is to communicate product change of select Renesas

Electronics America, Inc. (REA) devices.

Select SRAM products in SOP, μ TSOP, & BGA packages are undergoing the following changes (see the Appendix for specific details)...

- 1. Final Test Site change from Renesas Semiconductor Beijing to Powertech Technology Inc.
- 2. Standardization of JEDEC trays and Tape & Reel specifications.

There are no changes to part numbers, electrical characteristics, or reliability & quality levels.

Affected Products:

A review of our shipment records to your company indicate the attached list of products is affected by this notification.

	_
Booking Part Number	
R1LP0108ESN-5SI#B0	
R1LP0408DSP-5SI#B0	
R1LP5256ESP-5SI#B0	
R1LV0108ESN-5SI#B0	
R1LV5256ESP-5SI#B0	
RMLV0408EGSP-4S2#CA0	
RMLV0416EGBG-4S2#AC0	

Part numbers given in this list are for active part numbers in REA database at the time of this notification.

Key Dates:

Shipments from REA of products using the new Final Test Site and standardized JEDEC trays & Tape & Reel specifications begins. Cross shipments between the original and new products may continue for a period of time.

Dec. 15th, 2016

Response:

No response is required. REA will consider this notification approved 30 days after its issue. If you anticipate volumes beyond your regular rate prior to the transition date, please contact your REA sales representative with a forecast of your requirements.

Please contact your REA sales representative for any questions or comments.

Thank you for your attention.

Sincerely,

Renesas Electronics America, Inc.



Appendix A: Change Details

(1) 28pin-SOP 256Kb(5V) Part name: R1LP5256ESP

		Pre Change	Post Change
Orderable part name		R1LP5256ESP-5SI/-5SR/-7SI/-7SR#B0 (Magazine packing)	R1LP5256ESP-5SI#B0 (Magazine packing)
		R1LP5256ESP-5SI/-5SR/-7SI/-7SR#S0 (Tape & Reel packing)	R1LP5256ESP-5SI#S0 (Tape & Reel packing)
Assembly I		Renesas Semiconductor Beijing (China)	←
JEITA Package Code		P-SOP28-8.4x17.5-1.27	←
Package m specificatio		NAME	R1LP5256ESP Part name Electrical characteristics
	Lead frame material	42Alloy	+
Assembly	Lead plating	Sn-Cu	←
Material	Die bonding	Epoxy paste	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-Included)	+
inal test li	line		
		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
	Packing specification	Current specification	Powertech Technology Inc. (Taiwan) New specification
	specification Magazine		
_	specification Magazine Storage number	Current specification	New specification
_	specification Magazine Storage number Number of magazines (Max.)	Current specification Magagine code : MP024PC 30pcs/magazine 40 magazines	New specification ← ←
_	specification Magazine Storage number Number of magazines (Max.) Inner box size (LxWxH)	Current specification Magagine code : MP024PC 30pcs/magazine 40 magazines 600mm x 172mm x 77mm	New specification ← ← ← 595mm x 170mm x 72mm
packing	specification Magazine Storage number Number of magazines (Max.) Inner box size (LxWxH) Packing specification	Current specification Magagine code: MP024PC 30pcs/magazine 40 magazines 600mm x 172mm x 77mm Current specification	New specification ← ← 595mm x 170mm x 72mm New specification
Tape & Reel	specification Magazine Storage number Number of magazines (Max.) Inner box size (LxWxH) Packing specification Embossed tape	Current specification Magagine code : MP024PC 30pcs/magazine 40 magazines 600mm x 172mm x 77mm Current specification Emboss type name : MTE2416H-28P2W-C	New specification ← ← ← 595mm x 170mm x 72mm New specification ←
packing Tape & Reel	specification Magazine Storage number Number of magazines (Max.) Inner box size (LxWxH) Packing specification Embossed tape Storage number	Current specification Magagine code : MP024PC 30pcs/magazine 40 magazines 600mm x 172mm x 77mm Current specification Emboss type name : MTE2416H-28P2W-C 1,000pcs/reel	New specification ← ← 595mm x 170mm x 72mm New specification ← ←
Magazine packing Tape & Reel packing	specification Magazine Storage number Number of magazines (Max.) Inner box size (LxWxH) Packing specification Embossed tape Storage number Inner box size (LxWxH)	Current specification Magagine code: MP024PC 30pcs/magazine 40 magazines 600mm x 172mm x 77mm Current specification Emboss type name: MTE2416H-28P2W-C 1,000pcs/reel 347mm x 368mm x 54mm	New specification ← ← ← 595mm x 170mm x 72mm New specification ←
Pape & Reel	specification Magazine Storage number Number of magazines (Max.) Inner box size (LxWxH) Packing specification Embossed tape Storage number Inner box size (LxWxH) Storage number Inner box size (LxWxH)	Current specification Magagine code : MP024PC 30pcs/magazine 40 magazines 600mm x 172mm x 77mm Current specification Emboss type name : MTE2416H-28P2W-C 1,000pcs/reel	New specification ← ← 595mm x 170mm x 72mm New specification ← ←



Appendix A (cont.): Change Details
(2) 28pin-SOP 256Kb(3V) Part name : R1LV5256ESP

Item		Pre Change	Post Change
Orderable part name		R1LV5256ESP-5SI/-5SR/-7SI/-7SR#B0 (Magazine packing)	R1LV5256ESP-5SI#B0 (Magazine packing)
		R1LV5256ESP-5SI/-5SR/-7SI/-7SR#S0 (Tape & Reel packing)	R1LV5256ESP-5SI#S0 (Tape & Reel packing)
Assembly	line	Renesas Semiconductor Beijing (China)	←
JEITA Pac	kage Code	P-SOP28-8.4x17.5-1.27	←
Package n specification		NUMBER N	TOTAL COME XXXXXXXX Date code R1LV5256ESP Part name Electrical characteristics
	Lead frame	42Alloy	←
	material Lead plating	Sn-Cu	←
Assembly Material	Die bonding	Epoxy paste	-
Place lai	Wire bonding	Au	-
	Mold	Epoxy resin (Halogen-included)	÷
Final test I	- 10.0	Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Talwan)
	Packing specification	Current specification	New specification
	Magazine	Magagine code : MP024PC	←
Magazine packing	Storage number	30pcs/magazine	←
	Number of magazines (Max.)	40 magazines	←
	Inner box size (LxWxH)	600mm x 172mm x 77mm	595mm x 170mm x 72mm
	Packing specification Embossed	Current specification	New specification
Tape & Reel	tape	Emboss type name : MTE2416H-28P2W-C	←
packing	Storage number	1,000pcs/reel	←
****	Inner box size (LxWxH)	347mm x 368mm x 54mm	362mm x 340mm x 60mm
Moisture-p performan		MSL 2	←
Shipping I	abel	Current specification	No change in format (Changes in Renesas internal code)



(3) 32pin-SOP 1Mb(5V) Part name: R1LP0108ESN

Item		Pre Change	Post Change
Orderable part name		R1LP0108ESN-5SI/-5SR/-7SI/-7SR#B0 (Magazine packing)	R1LP0108ESN-5SI#B0 (Magazine packing)
Orderable	part name	R1LP0108ESN-5SI/-5SR/-7SI/-7SR#S0 (Tape & Reel packing)	R1LP0108ESN-5SI#S0 (Tape & Reel packing)
Assembly I		Renesas Semiconductor Beijing (China)	←
JEITA Pack	rage Code	P-SOP32-11.4x20.75-1.27	←
Package m specificatio	on	XXXXXXXX	R1LP0108ESN O Part name -5S1 Electrical characteristics
	Lead frame material	Cu	←
Assembly	Lead plating	Sn (pure tin)	←
Material	Die bonding	Epoxy paste	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-free)	←
Final test li	ine	Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
	Packing specification	Current specification	New specification
	Magazine	Magagine code : MP525PC	←
Magazine packing	Storage number	25pcs/magazine	←
	Number of magazines (Max.)	36 magazines	←
	Inner box size (LxWxH)	600mm x 172mm x 77mm	595mm x 170mm x 72mm
	Packing specification	Current specification	New specification
Tape & Reel	Embossed tape	Emboss type name : MTE3216H-32P2M-A	←
packing	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	347mm x 368mm x 54mm	362mm x 340mm x 60mm
Moisture-p performan		MSL 3	←
Shipping la	ahel	Current specification	No change in format (Changes in Renesas internal code)



(4) 32pin-SOP 1Mb(3V) Part name: R1LV0108ESN

Item		Pre Change	Post Change
Orderable part name		R1LV0108ESN-5SI/-5SR/-7SI/-7SR#B0 (Magazine packing)	R1LV0108ESN-5SI#B0 (Magazine packing)
		R1LV0108ESN-5SI/-5SR/-7SI/-7SR#S0 (Tape & Reel packing)	R1LV0108ESN-5SI#S0 (Tape & Reel packing)
Assembly	line	Renesas Semiconductor Beijing (China)	←
JEITA Pac	kage Code	P-SOP32-11.4x20.75-1.27	←
Package n specification	on	XXXXXXXX	XXXXXXXX Date code RILV0108ESN Part name Electrical characteristics
	Lead frame material	Cu	←
Assembly	Lead plating	Sn (pure tin)	←
Material	Die bonding	Epoxy paste	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-free)	←
Final test I	line	Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Talwan)
	Packing specification	Current specification	New specification
	Magazine	Magagine code : MP525PC	←
Magazine packing	Storage number	25pcs/magazine	←
	magazines (Max.) Inner box size	36 magazines	←
	(LxWxH) Packing	600mm x 172mm x 77mm	595mm x 170mm x 72mm
	specification Embossed	Current specification	New specification
Tape & Reel	tape Storage	Emboss type name : MTE3216H-32P2M-A	←
packing	number Inner box size	1,000pcs/reel	÷
Moisture-	(LxWxH)	347mm x 368mm x 54mm	362mm x 340mm x 60mm
performan	nce	MSL 3	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)



(5) 32pin-SOP 4Mb(5V) Part name: R1LP0408DSP

Item		Pre Change	Post Change
Orderable part name		R1LP0408DSP-5SI/-5SR/-7SI/-7SR#B0 (Magazine packing)	R1LP0408DSP-5SI#B0 (Magazine packing)
		R1LP0408DSP-5SI/-5SR/-7SI/-7SR#S0 (Tape & Reel packing)	R1LP0408DSP-5SI#S0 (Tape & Reel packing)
Assembly I	line	Renesas Semiconductor Beijing (China)	←
JEITA Pack	rage Code	P-SOP32-11.4x20.75-1.27	←
Package m specificatio		XXXXXXXX	XXXXXXXX Date code R1LP0408DSP Part name -5S1 Electrical characteristics
	Lead frame material	Cu	←
Assembly	Lead plating	Sn (pure tin)	←
Material	Die bonding	Epoxy paste	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-free)	←
Final test li	ine	Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
	Packing specification	Current specification	New specification
	Magazine	Magagine code : MP525PC	←
Magazine packing	Storage number	25pcs/magazine	←
	Number of magazines (Max.)	36 magazines	←
	Inner box size (LxWxH)	600mm x 172mm x 77mm	595mm x 170mm x 72mm
	Packing specification	Current specification	New specification
Tape & Reel	Embossed tape	Emboss type name : MTE3216H-32P2M-A	←
packing	Storage number	1,000pcs/reel	←
Malatron	Inner box size (LxWxH)	347mm x 368mm x 54mm	362mm x 340mm x 60mm
Moisture-p performan		MSL 3	←
Shipping la	abel	Current specification	No change in format (Changes in Renesas internal code)



(6) 32pin-SOP 4Mb(3V) Part name : RMLV0408EGSP

Item		Pre Change	Post Change
Orderable part name		RMLV0408EGSP-4S2#CA0 (Magazine packing)	←
Orderable part name		RMLV0408EGSP-4S2#HA0 (Tape & Reel packing)	←
Assembly I	line	Renesas Semiconductor Beijing (China)	←
JEITA Pack	kage Code	P-SOP32-11.4x20.75-1.27	←
Package marking specification		RMLV0408EGSP Date code RMLV0408EGSP Part name Electrical characteristics	No change
	Lead frame material	Cu	←
Assembly	Lead plating	Sn (pure tin)	←
Material	Die bonding	Epoxy paste	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-free)	←
Final test I	ine	Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
	Packing specification	Current specification	New specification
	Magazine	Magagine code : MP525PC	←
Magazine packing	Storage number	25pcs/magazine	←
	Number of magazines (Max.)	36 magazines	←
	Inner box size (LxWxH)	600mm x 172mm x 77mm	595mm x 170mm x 72mm
	Packing specification	Current specification	New specification
Tape &	Embossed tape	Emboss type name : MTE3216H-32P2M-A	(
Reel packing	Storage number	1,000pcs/reel	¢
	Inner box size (LxWxH)	347mm x 368mm x 54mm	362mm x 340mm x 60mm
Moisture-p performan		MSL 3	¢
Shipping la	abel	Current specification	No change in format (Changes in Renesas internal code)



(7) 48ball-FBGA 4Mb(3V) Part name: RMLV0416EGBG

Item		Pre Change	Post Change
Orderable part name		RMLV0416EGBG-4S2#AC0 (Tray packing)	←
Orderable part harrie		RMLV0416EGBG-4S2#KC0 (Tape & Reel packing)	+
Assembly	line	J-Devices Kumamoto District (Japan)	←
JEITA Pac	kage Code	P-TFBGA48-7.5x8.5-0.75	←
Package n specificati	on	RMLV0416EG BG-4S2 XXXXXXXX Date code	No change
	Substrate material	Glass epoxy	←
Assembly		Sn-Ag-Cu	←
Material	Die bonding	Epoxy paste	←
	Wire bonding	Ay	÷
	Mold	Epoxy resin (Halogen-free)	←
Final test	line	Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Talwan)
	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name: L196-45)	4
Tray	Storage number	253pcs/tray	←
packing	Laying direction of Ics on a tray	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)	4
	Number of trays (Max.)	9 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
	Packing specification	Current specification	New specification
Tape &	Embossed tape	Current specification	No change
packing	Storage number	1,000pcs/reel	(-
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture- performar		MSL 3	←
Shipping I	abel	Current specification	No change in format (Changes in Renesas internal code)



(8) 48ball-FBGA 8Mb(3V) Part name: RMLV0816BGBG

Item		Pre Change	Post Change
Orderable part name		RMLV0816BGBG-4S2#AC0 (Tray packing)	←
		RMLV0816BGBG-4S2#KC0 (Tape & Reel packing)	←
Assembly	line	J-Devices Kumamoto District (Japan)	←
JEITA Pac	kage Code	P-TFBGA48-7.5x8.5-0.75	←
Package n specification		RMLV0816BG BG-4S2 XXXXXXXX Date code	No change
	Substrate material	Glass epoxy	←
Assembly		Sn-Ag-Cu	←
Material	Die bonding	Epoxy paste	+
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-free)	←
Final test I	line	Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name : L196-45)	←
Tray	Storage number	253pcs/tray	←
packing	Laying direction of Ics on a tray	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)	←
	Number of trays (Max.)	9 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
	Packing specification	Current specification	New specification
Tape &	Embossed tape	Current specification	No change
packing	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture-p performan		MSL 3	←
Shipping I	abel	Current specification	No change in format (Changes in Renesas internal code)



(9) 48ball-FBGA 16Mb(3V) Part name: R1LV1616HBG

Item		Pre Change	Post Change
Orderable part name		R1LV1616HBG-4SI/-5SI#B0 (Tray packing)	←
Orderable	part name	R1LV1616HBG-4SI/-5SI#S0 (Tape & Reel packing)	←
Assembly line		J-Devices Kumamoto District (Japan)	←
JEITA Pack	kage Code	P-TFBGA48-8x9.5-0.75	←
Package m specification		R1LV1616H BG-4SI XXXXXXXX R1LV1616H BG-5SI XXXXXXXX Date code	No change
	Substrate material	Glass epoxy	+
Assembly	Solder ball	Sn-Ag-Cu	←
Material	Die bonding	Epoxy film	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-Included)	←
Final test I	ine	Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Talwan)
	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name: PTA71C)	←
Tray	Storage number	264pcs/tray	←
packing	Laying direction of Ics on a tray	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)	←
	Number of trays (Max.)	9 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
	Packing specification	Current specification	New specification
Tape & Reel	Embossed tape	Current specification	No change
packing	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture-p performan		MSL 3	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)

• Regarding R1LV1616HBG, laser marking on the package's surface is processed at final test site.



(10) 48ball-FBGA 16Mb(3V) Part name: RMLV1616AGBG

Item		Pre Change	Post Change
Orderable part name		RMLV1616AGBG-5S2#AC0 (Tray packing)	←
orderable part flame		RMLV1616AGBG-5S2#KC0 (Tape & Reel packing)	←
Assembly	line	J-Devices Kumamoto District (Japan)	←
JEITA Pac	kage Code	P-TFBGA48-7.5x8.5-0.75	-
Package r specificati	on	RMLV1616AG BG-5S2 XXXXXXXX Date code	No change
	Substrate material	Glass epoxy	←
Assembly	Solder ball	Sn-Ag-Cu	←
Material	Die bonding	Epoxy paste	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-free)	←
Final test	line	Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Talwan)
	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name : L196-45)	←
Tray	Storage number	253pcs/tray	←
packing	Laying direction of Ics on a tray	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)	←
	Number of trays (Max.)	9 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
	Packing specification	Current specification	New specification
Tape &	Embossed tape	Current specification	No change
packing	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture- performar		MSL 3	←
Shipping I	label	Current specification	No change in format (Changes in Renesas internal code)



Appendix A (cont.): Change Details
(11) 48ball-FBGA 32Mb(3V) Part name : RMWV3216AGBG

Item		Pre Change	Post Change
Orderable part name		RMWV3216AGBG-5S2#AC0 (Tray packing)	←
or delable pare marie		RMWV3216AGBG-5S2#KC0 (Tape & Reel packing)	←
Assembly	line	J-Devices Kumamoto District (Japan)	←
JEITA Pac	kage Code	P-TFBGA48-7.5x8.5-0.75	←
Package n specificati	on	RMWV3216AG BG-5S2 XXXXXXXX Date code Index mark	No change
	Substrate material	Glass epoxy	+
Assembly		Sn-Ag-Cu	←
Material	Die bonding	Epoxy film	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-free)	←
Final test		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name : L196-45)	←
Tray	Storage number	253pcs/tray	←
packing	Laying direction of Ics on a tray	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)	←
	Number of trays (Max.)	9 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
	Packing specification	Current specification	New specification
Tape &	Embossed tape	Current specification	No change
Reel packing	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture- performar		MSL 3	←
Shipping I	label	Current specification	No change in format (Changes in Renesas internal code)



(12) 48ball-FBGA 64Mb(3V) Part name: R1WV6416RBG

Item		Pre Change	Post Change
Orderable part name		R1WV6416RBG-5SI#B0 (Tray packing)	←
		R1WV6416RBG-5SI#S0 (Tape & Reel packing)	←
Assembly line		J-Devices Kumamoto District (Japan)	←
JEITA Pac	kage Code	P-TFBGA48-8.5x11-0.75	←
Package marking specification		R1WV6416RBG — Part name JAPAN -5SI — Electrical characteristics XXXXXXXXX Date code Index mark Country of origin (Back-End Line: Assembly)	No change
	Substrate material	Glass epoxy	←
Assembly		Sn-Ag-Cu	←
Material	Die bonding	Epoxy film	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-Included)	←
Final test	line	Renesas Semiconductor Beljing (China)	Powertech Technology Inc. (Talwan)
	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name: L196-121)	4
Tray	Storage number	242pcs/tray	4
packing	Laying direction of Ics on a tray	Direction from the bottm right position to the up side (when the position of chamfer in tray's corner is bottom left.)	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)
	Number of trays (Max.)	8 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Current specification	No change
	Storage number	1,000pcs/reel	4
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture-proof performance		MSL 3	←
Shipping I	label	Current specification	No change in format (Changes in Renesas internal code)



(13) 52pin-µTSOP 8Mb(3V) Part name : RMLV0816BGSD

Item		Pre Change	Post Change
Orderable part name		RMLV0816BGSD-4S2#AC0 (Tray packing)	+
		RMLV0816BGSD-4S2#HC0 (Tape & Reel packing)	←
Assembly line		Renesas Semiconductor Beijing (China)	←
JEITA Package Code		P-TSOP(2)52-8.89x10.79-0.40	←
Package marking specification		RMLV0816BG Part name, Electrical characteristics XXXXXXXXX Date code	No change
	Lead frame	42Alloy	+
	material		
Assembly	Lead plating	Sn-Cu	←
Material	Die bonding	Epoxy film	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-included)	←
Final test I		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name : L196-24)	←
Tray	Storage number	230pcs/tray	←
packing	Laying direction of Ics on a tray	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)	←
	Number of trays (Max.)	8 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
	Packing specification	Current specification	New specification
Tape & Reel packing	Embossed tape	Current specification	No change
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture-proof performance		MSL 2	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)



(14) 52pin-µTSOP 16Mb(3V) Part name : RMLV1616AGSD

Item		Pre Change	Post Change
Orderable part name		RMLV1616AGSD-5S2#AC0 (Tray packing)	←
or delable part flame		RMLV1616AGSD-5S2#HC0 (Tape & Reel packing)	←
Assembly line		Renesas Semiconductor Beijing (China)	←
JEITA Pad	kage Code	P-TSOP(2)52-8.89x10.79-0.40	←
Package marking specification		RMLV1616AG SD-5S2 XXXXXXXXX Defe code	No change
	Lead frame	42Alloy	←
	material Lead plating	Sn-Cu	+
Assembly Material	Die bonding	Epoxy film	÷
Material	Wire bonding	Au	-
	Mold	Epoxy resin (Halogen-included)	←
Final test I	- 10.0	Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Talwan)
T II III COOK	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name: L196-24)	4
Tray	Storage number	230pcs/tray	←
packing	Laying direction of Ics on a tray	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)	4
	Number of trays (Max.)	8 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Current specification	No change
	Storage number	1,000pcs/reel	4
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture-proof performance		MSL 2	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)



(15) 52pin-µTSOP 32Mb(3V) Part name : R1LV3216RSD

Item		Pre Change	Post Change
Orderable part name		R1LV3216RSD-5SI#B0 (Tray packing)	←
or derable part name		R1LV3216RSD-5SI#S0 (Tape & Reel packing)	←
Assembly line		Renesas Semiconductor Beijing (China)	←
JEITA Pac	kage Code	P-TSOP(2)52-8.89x10.79-0.40	←
Package marking specification		R1LV3216R SD-5SI Characteristics XXXXXXXXX Dete code	No change
	Lead frame material	42Alloy	←
Assembly		Sn-Cu	÷
Material	Die bonding	Epoxy film	÷
1-later lai	Wire bonding	Au	÷
	Mold	Epoxy resin (Halogen-included)	÷
Final test I		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Talwan)
	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name: L196-24)	←
Tray	Storage number	230pcs/tray	←
packing	Laying direction of Ics on a tray	Direction from the bottm right position to the up side (when the position of chamfer in tray's corner is bottom left.)	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)
	Number of trays (Max.)	8 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
	Packing specification	Current specification	New specification
Tape & Reel packing	Embossed tape	Current specification	No change
	Storage number	1,000pcs/reel	«
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture-proof performance		MSL 2	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)



(16) 52pin-µTSOP 64Mb(3V) Part name: R1WV6416RSD

Item		Pre Change	Post Change
Orderable part name		R1WV6416RSD-5SI#B0 (Tray packing)	←
Orderable part name		R1WV6416RSD-5SI#S0 (Tape & Reel packing)	←
Assembly line		Renesas Semiconductor Beijing (China)	←
JEITA Pac	kage Code	P-TSOP(2)52-8.89x10.79-0.40	←
Package marking specification		R1WV6416R SD-5S I Slectrical Characteristics XXXXXXXXX Date code	No change
	Lead frame	42Alloy	+
	material		
Assembly	Lead plating	Sn-Cu	←
Material	Die bonding	Epoxy film	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-Included)	+
Final test I		Renesas Semiconductor Beljing (China)	Powertech Technology Inc. (Taiwan)
	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name : L196-24)	←
Tray	Storage number	230pcs/tray	←
packing	Laying direction of Ics on a tray	Direction from the bottm right position to the up side (when the position of chamfer in tray's corner is bottom left.)	Direction from the top left position to the down side (when the position of chamfer in tray's comer is bottom left.)
	Number of trays (Max.)	8 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
	Packing specification	Current specification	New specification
Tape & Reel packing	Embossed tape	Current specification	No change
	Storage number	1,000pcs/reel	« -
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture-proof performance		MSL 2	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)



Appendix B: Packaging Specification Change

- Regarding R1LV3216RSD-5SI, R1WV6416RSD-5SI and R1WV6416RBG-5SI, laying direction of ICs on a tray is to be changed (see below).
- No change in other products, because the direction is already same as the "Post Change" as shown below.

	Pre Change	Post Change
Laying direction of ICs on a tray	Direction 1	Direction
Orderable part name	R1LV3216RSD-5SI#B0 R1WV6416RSD-5SI#B0 R1WV6416RBG-5SI#B0	R1LV3216RSD-5SI#B0 R1WV6416RSD-5SI#B0 R1WV6416RBG-5SI#B0